

KIT, DETERGENT COMPOSITION, AND METHOD FOR MANUFACTURING SEMICONDUCTOR ELEMENT

ABSTRACT

Provided are a kit including a temporary bonding material and a detergent composition, the kit being capable of suitably removing a residue derived from the temporary bonding material including a silicone compound; a detergent composition; and a method for manufacturing a semiconductor element. The kit includes a detergent composition including an acid or base and an organic solvent, and a temporary bonding material including a silicone compound, in which a value represented by Formula (a) of the acid is 0 to 10, and a value represented by Formula (b) of the base is -5 to 0;

Formula (a) ClogP-pKa

Formula (b) ClogP-pKb

in Formulae (a) and (b), ClogP represents a value represented by a base-10 logarithm $\log P$ of P which is a 1-octanol/water partition coefficient representing a ratio of an equilibrium concentration in 1-octanol and water, pKa represents an acid dissociation constant, and pKb represents a base dissociation constant.

[No suitable figure]